



Material Content Data Sheet



Sales Product Name				IPG20N10S4L-22A		Issued		12. February 2019	
MA#				MA002193068					
Package				PG-TDSON-8-10		Weight*		100.37 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	1.632	1.63	1.63	16256	16256	
chip_2	inorganic material	silicon	7440-21-3	1.632	1.63	1.63	16256	16256	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		131		
	non noble metal	iron	7439-89-6	0.044	0.04		436		
	non noble metal	copper	7440-50-8	43.681	43.52	43.57	435186	435753	
	non noble metal	aluminium	7429-90-5	0.779	0.78	0.78	7761	7761	
wire	non noble metal	aluminium	7429-90-5	0.779	0.78	0.78	7761	7761	
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		884		
	plastics	epoxy resin	-	6.298	6.27		62743		
	inorganic material	silicondioxide	60676-86-0	37.964	37.82	44.18	378226	441853	
leadfinish	non noble metal	tin	7440-31-5	1.396	1.39	1.39	13912	13912	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		14		
	non noble metal	nickel	7440-02-0	0.603	0.60	0.60	6008	6022	
solder	non noble metal	tin	7440-31-5	0.071	0.07		705		
	noble metal	silver	7440-22-4	0.088	0.09		882		
	non noble metal	lead	7439-92-1	3.380	3.37	3.53	33677	35264	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		8		
	non noble metal	iron	7439-89-6	0.003	0.00		27		
	non noble metal	copper	7440-50-8	2.699	2.69	2.69	26888	26923	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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